IEC 61188-6-1

Edition 1.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE

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Circuit boards and circuit board assemblies – Design and use – Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

Cartes imprimées et cartes imprimées équipées – Conception et utilisation – Partie 6-1: Conception de la zone de report – Exigences génériques pour la zone de report sur les cartes imprimées

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

FOREWORD

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IEC 61188-6-1 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This first edition cancels and replaces the first edition of IEC 61188-5-1 published in 2002, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) The content is completely updated to reflect current industry requirements. See Introduction.

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1636/CDV	91/1671/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61188 series, published under the general title *Circuit boards and circuit board assemblies – Design and use*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
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- replaced by a revised edition, or
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INTRODUCTION

Explanation why the following standards will be replaced by the new IEC 6188-6 series:

IEC 61188-5-1:2002, *Printed boards and printed board assemblies – Design and use – Part 5-1: Attachment (land/joint) considerations – Generic requirements*

IEC 61188-5-2:2003, *Printed boards and printed board assemblies – Design and use – Part 5-2: Attachment (land/joint) considerations – Discrete components*

IEC 61188-5-3:2007, *Printed boards and printed board assemblies – Design and use – Part 5-3: Attachment (land/joint) considerations – Components with gull-wing leads on two sides*

IEC 61188-5-4:2007, *Printed boards and printed board assemblies – Design and use – Part 5-4: Attachment (land/joint) considerations – Components with J leads on two sides*

IEC 61188-5-5:2007, *Printed boards and printed board assemblies – Design and use – Part 5-5: Attachment (land/joint) considerations – Components with gull-wing leads on four sides*

IEC 61188-5-6:2003, *Printed boards and printed board assemblies – Design and use – Part 5-6: Attachment (land/joint) considerations – Chip carriers with J-leads on four sides*

IEC 61188-5-8:2007, *Printed board and printed board assemblies – Design and use – Part 5-8: Attachment (land/joint) considerations – Area array components (BGA, FBGA, CGA, LGA)*

Content is mostly equivalent to IPC-782A with Amendments 1 and 2, which was replaced in 2002 by IPC-7351. The component spectrum and pitch levels have dramatically increased since publication of the IEC 61188-5 (all parts) and the dimensioning concept does no longer fulfil the mounting and soldering requirements.

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards

1 Scope

This part of IEC 61188 specifies the requirements for soldering surfaces on circuit boards. This includes lands and land pattern for surface mounted components and also solderable hole configurations for through-hole mounted components. These requirements are based on the solder joint requirements of the IEC 61191-1, IEC 61191-2, IEC 61191-3 and IEC 61191-4.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IEC 61191-2:2017, *Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*

IEC 61760-3, *Surface mounting technology – Part 3: Standard method for the specification of components for through hole reflow (THR) soldering*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194, and the following apply.

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